Modification history

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| Release | Comments |
| Release 1 | This version released with FBP Food, Beverage and Pharmaceutical Training Package Version 1. |

| FBPPBK2004 | Manufacture wafer products |
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| Application | This unit of competency describes the skills and knowledge required to set up, operate, adjust and shut down a wafer products manufacturing process.  This unit applies to individuals who work in a baking production environment under general supervision with some accountability for their own work. This includes identifying and providing solutions to a limited range of predictable problems relating to the operation and monitoring of machines and equipment used in the wafer manufacturing process.  All work must be carried out to comply with workplace procedures, in accordance with State/Territory work health and safety, and food safety regulations, legislation and standards that apply to the workplace.  No occupational licensing, legislative or certification requirements apply to this unit at the time of publication. |
| Prerequisite Unit | Nil |
| Unit Sector | Production baking (PBK) |

| Elements | Performance Criteria |
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| Elements describe the essential outcomes. | Performance criteria describe the performance needed to demonstrate achievement of the element. |
| 1. Prepare the wafer process for operation | 1.1 Read or listen to work instructions from supervisor and clarify where needed  1.2 Identify work health and safety hazards and report to supervisor  1.3 Wear appropriate personal protective equipment and ensure correct fit  1.4 Confirm availability of materials to meet production requirements  1.5 Identify and confirm cleaning and maintenance requirements have been met  1.6 Fit machine components and related attachments and adjust to meet operating requirements  1.7 Select processing and operating parameters to meet safety and production requirements  1.8 Check equipment and adjust according to manufacturer instructions to ensure optimum performance  1.9 Carry out pre-start checks according to operator instructions |
| 2. Operate and monitor the wafer process | 2.1 Start the wafer products manufacturing process according to workplace procedures  2.2 Monitor equipment to identify variation in operating conditions and report variations in equipment operation  2.3 Monitor the process to confirm that product meets specifications  2.4 Identify, rectify and report out-of-specification product and process outcomes  2.5 Conduct work and maintain a clean and tidy workplace according to workplace environmental guidelines |
| 3. Shut down the process | 3.1 Identify the appropriate shutdown procedure and implement  3.2 Identify and report maintenance requirements  3.3 Maintain workplace records accurately according to workplace procedures |

| Foundation Skills  This section describes those language, literacy, numeracy and employment skills that are essential for performance in this unit of competency but are not explicit in the performance criteria. | |
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| Skill | Description |
| Reading | * Interpret text in work instructions and production schedule and recognise workplace signage |
| Numeracy | * Interpret symbols and numbers to calibrate equipment and set oven temperatures and processing parameters * Use basic arithmetic to calculate quantities of wafer batter * Measure wafer width, length and thickness against specifications |
| Oral communication | * Participate in verbal exchanges to ask questions and convey workplace information |
| Navigate the world of work | * Recognise and follow workplace requirements, including safety, quality, food safety and environmental requirements, associated with own role and area of responsibility |
| Interact with others | * Follow accepted practices and protocols for reporting issues to supervisors |
| Get the work done | * Follow clearly defined instructions to plan and assemble resources and sequence tasks to manufacture wafer products * Monitor processes and control points, identify routine problems related to own work or role, and initiate standard procedures to resolve * Use key functions and follow routine procedures for using digital technology and automated equipment |

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| Unit Mapping Information | | | |
| Code and title current version | Code and title previous version | Comments | Equivalence status |
| FBPPBK2004 Manufacture wafer products | FDFBK2004A Manufacture wafer products | Updated to meet Standards for Training Packages  Minor changes to performance criteria for clarity | Equivalent unit |

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| Links | Companion Volumes, including Implementation Guides, are available at VETNet:  https://vetnet.education.gov.au/Pages/TrainingDocs.aspx?q=78b15323-cd38-483e-aad7-1159b570a5c4 |

| TITLE | Assessment requirements for FBPPBK2004 Manufacture wafer products |
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| Performance Evidence | |
| An individual demonstrating competency must satisfy all of the elements and performance criteria in this unit.  There must be evidence that the individual has set up, operated, adjusted and shut down a wafer manufacturing process on at least three separate occasions, including:   * accessing workplace information to identify wafer production requirements * selecting, fitting and using personal protective equipment * confirming supply of necessary materials and services, including confirming quality, quantity and temperature of batter * conducting pre-start checks, including: * inspecting equipment condition to identify any signs of wear * selecting appropriate settings and/or related parameters * cancelling isolation or lock outs * confirming that related equipment is clean and correctly configured for processing requirements * positioning sensors and controls correctly * ensuring scheduled maintenance has been carried out * confirming that all safety guards are in place and operational * ensuring correct batter is supplied and confirm settings, including: * wafer plates are selected for product type * oven settings for product type * web/chain speed settings * depositing rate settings * starting, operating, monitoring and adjusting process equipment to achieve required outcomes, including monitoring control points and conducting inspections as required to confirm process remains within specification, including: * wafer size (width, length and thickness) * wafer texture, colour and weight * wafer moisture level * using process control systems according to workplace procedures * monitoring supply and flow of materials to and from the process * taking corrective action in response to out-of-specification results in line with own role and responsibilities * following work health and safety procedures, including: * responding to and/or reporting equipment failure * locating emergency stop functions on equipment * shutting down equipment in response to an emergency situation * following isolation and lock out/tag out procedures to take process and related equipment off-line in preparation for cleaning and/or maintenance within level of responsibility * completing workplace records as required * applying environmental and food safety policies and procedures to work practices, including: * maintaining work area to meet housekeeping standards * cleaning and sanitising equipment according to workplace procedures. | |

| Knowledge Evidence |
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| An individual must be able to demonstrate the knowledge required to perform the tasks outlined in the elements and performance criteria of this unit. This includes knowledge of:   * purpose and basic principles of each stage of the wafer manufacturing process * basic operating principles of equipment, including: * main equipment components * status and purpose of guards * equipment operating capacities and applications * purpose and location of sensors and related feedback instrumentation * typical equipment faults and related causes, including signs and symptoms of faulty equipment, loss of power, and early warning signs of potential problems * the flow of the wafer manufacturing process and the effect of outputs on downstream processes * basic operating principles of process control, including the relationship between control panels and systems and wafer products manufacturing equipment * specifications and quality characteristics to be achieved by the wafer manufacturing process, including: * quality requirements of materials * effect of variation on wafer manufacturing process performance * changes which occur in product during processing * operating requirements and parameters and corrective action required where operation is outside specified operating parameters * methods used to monitor the wafer manufacturing process, including: * inspecting, measuring and testing as required by the wafer products manufacturing process * inspection or test points (control points) in the process * related procedures and recording requirements * common causes of variation and corrective action required * work health and safety hazards and controls, including: * routine shut down for wafer manufacturing process * emergency shut downs * procedures to follow in the event of a power outage * isolation, lock out and tag out procedures and responsibilities * procedures and responsibility for reporting production and performance information * environmental and food safety issues and controls relevant to the wafer manufacturing process, including: * waste and rework collection and handling procedures * contamination and food safety risks * cleaning and sanitation procedures. |

| Assessment Conditions |
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| Assessment of this unit of competency must take place under the following conditions:   * physical conditions: * a commercial bakery or an environment that accurately represents workplace conditions * resources, equipment and material: * cleaning procedures, materials and equipment * personal protective clothing and equipment * depositing, baking, and related equipment used in wafer production * wafer plates * batter to meet production requirements * documentation or technology for recording information * specifications: * work instructions including control points and wafer manufacturing processing parameters * production schedule and recipe and batch specifications for wafer products * workplace procedures for operating wafer products manufacturing process * information on equipment capacity and operating parameters * relationships (internal and/or external): * workplace supervisor * timeframes: * according to work requirements.   Assessors of this unit must satisfy the requirements for assessors in applicable vocational education and training legislation, frameworks and/or standards. |

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